

CLOTHESPIN TYPE HEAT DISSIPATING APPARATUS FOR SEMICONDUCTOR MODULE

ABSTRACT OF THE DISCLOSURE

Some embodiments of the invention include two heat exchange members, which are arranged facing each other with a semiconductor module therebetween, the semiconductor module including a plurality of packages; a connection member formed in the middle of each of the heat exchange members to hinge join the heat exchange members such that portions of the heat exchange members protrude above the semiconductor module inserted between the heat exchange members; and an elastic member disposed between the heat exchange members to provide a force pushing portions of the heat exchange members below the connection member toward the packages of the semiconductor module. Other embodiments of the invention are described in the claims.